

## **PALM INTRANET**

Day: Monday Date: 10/18/2004 Time: 11:13:09

#### **Inventor Name Search Result**

Your Search was:

Last Name = LANE

First Name = RYAN

Application#	Patent#	Status	Date Filed	Title	Inventor Name 9
<u>60569187</u>	Not Issued	020	05/07/2004	VIDEO GAME PLATFORM AND USER INTERFACE	LANE, RYAN THOMAS
<u>60547756</u>	Not Issued	020	02/24/2004	OPTIMIZED POWER DELIVERY TO HIGH SPEED, HIGH PIN COUNT DEVICES	LANE, RYAN
<u>60465303</u>	Not Issued	159	04/24/2003	TECHNIQUE FOR STACKING VARIABLE SIZE DICE IN A PACKAGE WITH WIRE BOND AND FLIP CHIP TECHNOLOGY	LANE, RYAN
<u>60443817</u>	Not Issued	159	01/30/2003	AREA ARRAY PACKAGE WITH IMPROVED RELIABILITY OF SOLDER JOINTS	LANE, RYAN
60399091	Not Issued	159	07/26/2002	LAMINATE SUBSTRATE DESIGN FEATURES TO ACCOMMODATE SMALLER MINIMUM IN AREA ARRAY PACKAGES WITH WIREBOND TECHNOLOGY	LANE, RYAN
<u>10830188</u>	Not Issued	030	04/21/2004	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	LANE, RYAN
<u>10624787</u>	Not Issued	071	07/21/2003	METHOD FOR A ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	LANE, RYAN
<u>10443524</u>	Not Issued	161	05/21/2003	TECHNIQUE FOR STACKING VARIABLE SIZE DICE IN A PACKAGE WITH WIRE BOND AND FLIP CHIP TECHNOLOGY	LANE, RYAN

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	Last Name	First Name
Search Another:	LANE	RYAN
Inventor		Search

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Day: Monday Date: 10/18/2004 Time: 11:13:35

#### **Inventor Name Search Result**

Your Search was:

Last Name = REYES

First Name = EDWARD

Application#	Patent#	Status	Date Filed	Title	Inventor Name 10
60465303	Not Issued	159	04/24/2003	TECHNIQUE FOR STACKING VARIABLE SIZE DICE IN A PACKAGE WITH WIRE BOND AND FLIP CHIP TECHNOLOGY	REYES, EDWARD
<u>60443817</u>	Not Issued	159	01/30/2003	AREA ARRAY PACKAGE WITH IMPROVED RELIABILITY OF SOLDER JOINTS	REYES, EDWARD
60399091	Not Issued	159	07/26/2002	LAMINATE SUBSTRATE DESIGN FEATURES TO ACCOMMODATE SMALLER MINIMUM IN AREA ARRAY PACKAGES WITH WIREBOND TECHNOLOGY	REYES, EDWARD
<u>10830188</u>	Not Issued	030	04/21/2004	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	REYES, EDWARD
<u>10624787</u>	Not Issued	071	07/21/2003	METHOD FOR A ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	REYES, EDWARD
10443524	Not Issued	161	05/21/2003	TECHNIQUE FOR STACKING VARIABLE SIZE DICE IN A PACKAGE WITH WIRE BOND AND FLIP CHIP TECHNOLOGY	REYES, EDWARD
<u>10393666</u>	6762495	150	03/20/2003	AREA ARRAY PACKAGE WITH NON-ELECTRICALLY CONNECTED SOLDER BALLS	REYES, EDWARD
10282795	6787901	150	10/28/2002	METHOD AND APPARATUS	REYES,

				FOR DIE STACKING	EDWARD
09932160	6680219	150	08/17/2001		REYES, EDWARD
08282205	<u>5407082</u>	150		AUTOMATIC EJECTOR RATE NORMALIZER USING MULTIPLE TRIP LEVELS ESTABLISHED IN A MASTER CHANNEL	EDWARD G.

Inventor Search Completed: No Records to Display.

	Last Name	First Name
Search Another:	REYES	EDWARD
Inventor		Search

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Day: Monday Date: 10/18/2004 Time: 11:14:28

#### **Inventor Name Search Result**

Your Search was:

Last Name = VEATCH

First Name = MARK

Application#	Patent#	Status	Date Filed	Title	Inventor Name 5
<u>60547756</u>	Not Issued	020	02/24/2004	OPTIMIZED POWER DELIVERY TO HIGH SPEED, HIGH PIN COUNT DEVICES	VEATCH, MARK
<u>60399091</u>	Not Issued	159	07/26/2002	LAMINATE SUBSTRATE DESIGN FEATURES TO ACCOMMODATE SMALLER MINIMUM IN AREA ARRAY PACKAGES WITH WIREBOND TECHNOLOGY	VEATCH, MARK
10830188	Not Issued	030	04/21/2004	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	VEATCH, MARK
<u>10624787</u>	Not Issued	071	07/21/2003	METHOD FOR A ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	VEATCH, MARK
<u>07162166</u>	4866660	150	02/29/1988	OPTOELECTRONIC DEVICES BASED ON INTERFERENCE INDUCED CARRIER MODULA- TION	VEATCH, MARK S.

Inventor Search Completed: No Records to Display.

	Last Name	First Name	
Search Another:	VEATCH	MARK	
Inventor		Search	

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# PALM INTRANET

Day: Monday Date: 10/18/2004 Time: 11:14:36

### **Inventor Name Search Result**

Your Search was:

Last Name = GREGORICH

First Name = TOM

Application#	Patent#	Status	Date Filed	Title	Inventor Name 7
60525540	Not Issued	020	11/25/2003	USE (SMP) STACKED MODULE PACKAGE TO DECOUPLE AND STANDARDIZE THE INTERFACE BETWEEN MULTIPLE DIE IN ONE PACKAGE	GREGORICH, TOM
60524331	Not Issued	020	11/21/2003	USE (MIP) MODULE-IN-PACKAGE SOLUTION TO DECOUPLE AND STANDARDIZE DIGITAL AND MEMORY INTERFACE	GREGORICH, TOM
60443817	Not Issued	159	01/30/2003	AREA ARRAY PACKAGE WITH IMPROVED RELIABILITY OF SOLDER JOINTS	GREGORICH, TOM
60399091	Not Issued	159	07/26/2002	LAMINATE SUBSTRATE DESIGN FEATURES TO ACCOMMODATE SMALLER MINIMUM IN AREA ARRAY PACKAGES WITH WIREBOND TECHNOLOGY	GREGORICH, TOM
<u>10830188</u>	Not Issued	030	04/21/2004	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	GREGORICH, TOM
<u>10624787</u>	Not Issued	071	07/21/2003	METHOD FOR A ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	GREGORICH, TOM
10393666	6762495	150	03/20/2003	AREA ARRAY PACKAGE WITH NON-ELECTRICALLY CONNECTED SOLDER	GREGORICH, TOM

Inventor Search Co	***************************************	ls to Display.	
•	Last Name	First Name	
Search Another:	GREGORÍCH	TOM	
Inventor		Search	

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	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	195	array and die same attach\$ and bond\$ with wire and bond same finger	US-PGPUB; EPO;	2004/10/15 16:59
2	BRS	172	array and die same attach\$ and bond\$ with wire and bond same (staggered or offset or offest)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
3	BRS	2	substrate and die and bond adj pad and bond adj island and wire adj bond and (enapsulating encapsulate encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:15
4	BRS	599	substrate and die and bond adj pad and wire adj bond and (enapsulating encapsulate encapsulated)	US-PGPUB; EPO;	2004/10/15 17:15
5	BRS	25	substrate and die and bond adj pad and wire adj bond and (enapsulating encapsulate encapsulated) and BGA and LGA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
6	BRS	4	("5545923" "6407456").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:19
7	BRS	325	438/617.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:45

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